

**AMENDMENTS TO THE CLAIMS**

Please amend the claims as follows.

1. (Currently Amended) A method for manufacturing a probe card, which comprises a contact provided on a base substrate and electrically coupled to a terminal of an electronic device, for receiving and/or sending a signal from and/or to said electronic device, comprising:
  - a first contact formation step of forming a first contact ~~of said contacts~~ on a first surface of a first sacrificial substrate;
  - a second contact formation step of forming a second contact ~~of said contacts of~~ on a first surface of a second sacrificial substrate;
  - a signal transmission line formation step of forming a signal transmission line in said base substrate;
  - a first contact joining step of attaching said first surface of said first sacrificial substrate to said base substrate and joining said first contact to said signal transmission line; [[and]]
  - a second contact joining step of attaching said first surface of said second sacrificial substrate to said base substrate and joining said second contact to said signal transmission line; and
  - a first sacrificial substrate elimination step of eliminating said first sacrificial substrate after said first contact is coupled to said signal transmission line in said first contact joining step.
2. (Currently Amended) [[A]] The method for manufacturing a probe card as claimed in claim 1, ~~further comprising:~~
  - ~~a first sacrificial substrate elimination step of eliminating said first sacrificial substrate after said first contact is coupled to said signal transmission line in said first contact joining step;~~
  - wherein after said first sacrificial substrate is eliminated in said first sacrificial substrate elimination step, said first surface of said second sacrificial substrate is attached to said base substrate and said second contact is joined to said signal transmission line in said second contact joining step.

3. (Currently Amended) [[A]] The method for manufacturing a probe card as claimed in claim 1, wherein said first contact formation step comprises the steps of:
- forming a first penetration hole in said first sacrificial substrate; and
  - forming a first one of said first contact[[s]] in order that a first end of said first one of said first contact[[s]] is fixed to said first surface of said first sacrificial substrate and a second end of said first one of said first contact[[s]] is bent in a direction toward a second surface opposite to said first surface of said first sacrificial substrate to be held freely within said first penetration hole.
4. (Currently Amended ) [[A]] The method for manufacturing a probe card as claimed in claim 3, wherein said first contact formation step comprises a step of:
- forming a second one of said first contact[[s]] in order that a first end of said second one of said first contact[[s]] is fixed to said first surface of said first sacrificial substrate at a position facing said first one of said first contact[[s]] to said first penetration hole and a second end of said second one of said first contact[[s]] is bent in said direction toward said second surface of said first sacrificial substrate to be held freely within said first penetration hole.
5. (Currently Amended) [[A]] The method for manufacturing a probe card as claimed in claim 4, wherein said first contact formation step comprises a step of:
- forming said first and second ones of said first contact[[s]] to be substantially symmetrical at two facing sides of said first penetration hole formed in a rectangular shape respectively.
6. (Withdrawn) A method for manufacturing a probe card as claimed in claim 3, wherein said first contact formation step comprises a step of:
- forming a plurality of said first contacts at each of four sides of said first penetration hole formed in a rectangular shape.
7. (Withdrawn) A method for manufacturing a probe card as claimed in claim 3, wherein said second contact formation step comprises the steps of:
- forming a second penetration hole which is larger than an area of said first sacrificial substrate in which said first contact is placed; and

forming said second contact in order that a first end of said second contact is fixed to said first surface of said second sacrificial substrate and a second end of said second contact is bent in a direction toward a second surface opposite to said first surface of said second sacrificial substrate to be held freely within said second penetration hole, and said second joining step comprises a step of:

attaching said first surface of said second sacrificial substrate to said base substrate in order that said first contact coupled with said signal transmission line is placed within said second penetration hole and joining said second contact to said signal transmission line.

8. (Canceled)

9. (New) A method for manufacturing a probe card, which comprises a contact provided on a base substrate and electrically coupled to a terminal of an electronic device, for receiving and/or sending a signal from and/or to said electronic device, comprising:

- a first contact formation step of forming a first contact on a first surface of a first sacrificial substrate, said first contact including a first end which is fixed to the first surface of the first sacrificial substrate and a second end which is freely held at the outside of the first sacrificial substrate in a direction parallel to the first surface of the first sacrificial substrate;

- a second contact formation step of forming a second contact on a first surface of a second sacrificial substrate, said second contact including a third end which is fixed to the first surface of the second sacrificial substrate and a fourth end which is freely held at the outside of the second sacrificial substrate in a direction parallel to the first surface of the second sacrificial substrate;

- a signal transmission line formation step of forming a signal transmission line in said base substrate;

- a first contact joining step of attaching said first surface of said first sacrificial substrate to said base substrate and joining said first contact to said signal transmission line; and

a second contact joining step of attaching said first surface of said second sacrificial substrate to said base substrate and joining said second contact to said signal transmission line.

10. (New) The method for manufacturing a probe card as claimed in claim 9, further comprising a first sacrificial substrate elimination step of eliminating said first sacrificial substrate after said first contact is coupled to said signal transmission line in said first contact joining step.

11. (New) The method for manufacturing a probe card as claimed in claim 10, wherein after said first sacrificial substrate is eliminated in said first sacrificial substrate elimination step, said first surface of said second sacrificial substrate is attached to said base substrate and said second contact is joined to said signal transmission line in said second contact joining step.

12. (New) The method for manufacturing a probe card as claimed in claim 9, wherein said first contact formation step comprises a step of:

forming a first one of said first contact in order that a first end of said first one of said first contact is fixed to said first surface of said first sacrificial substrate and a second end of said first one of said first contact is bent in a direction toward a second surface opposite to said first surface of said first sacrificial substrate to be held freely at the outside of the first sacrificial substrate.

13. (New) The method for manufacturing a probe card as claimed in claim 12, wherein said first contact formation step comprises a step of:

forming a second one of said first contact in order that a first end of said second one of said first contact is fixed to said first surface of said first sacrificial substrate at a position adjacent to said first one of said first contact and a second end of said second one of said first contact is bent in said direction toward said second surface of said first sacrificial substrate to be held freely at the outside of the first sacrificial substrate.